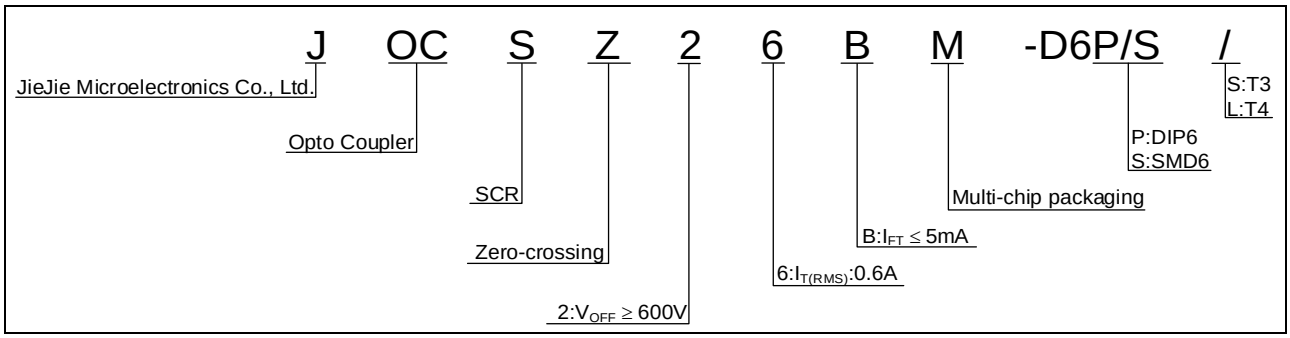
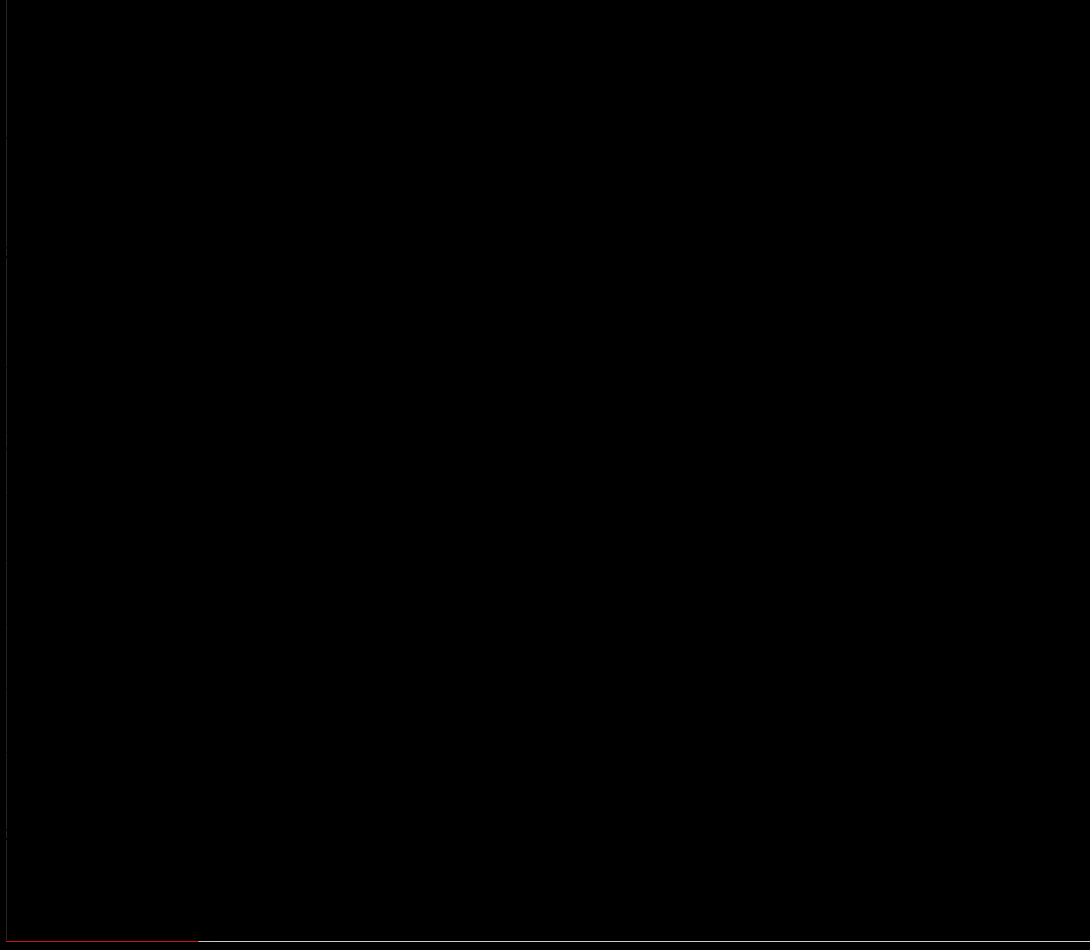
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ORDERING INFORMATION

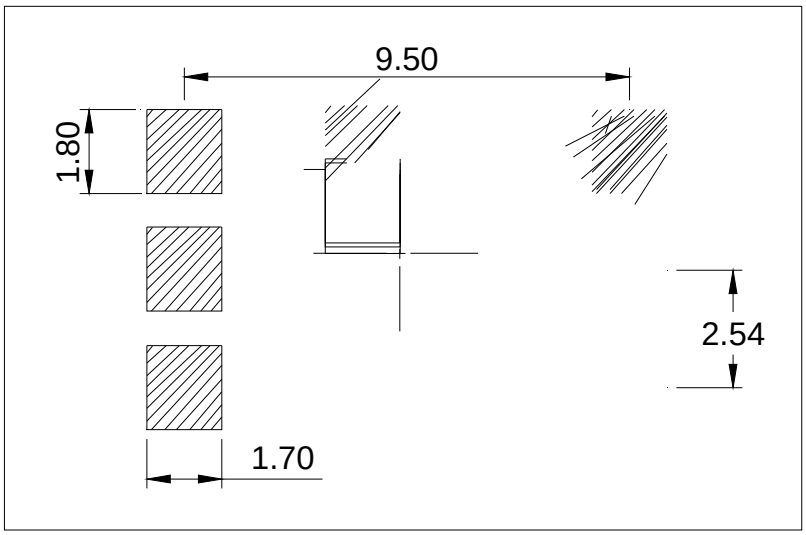




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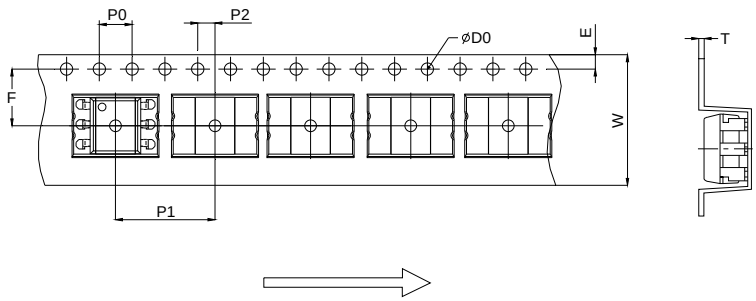
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SMD



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S

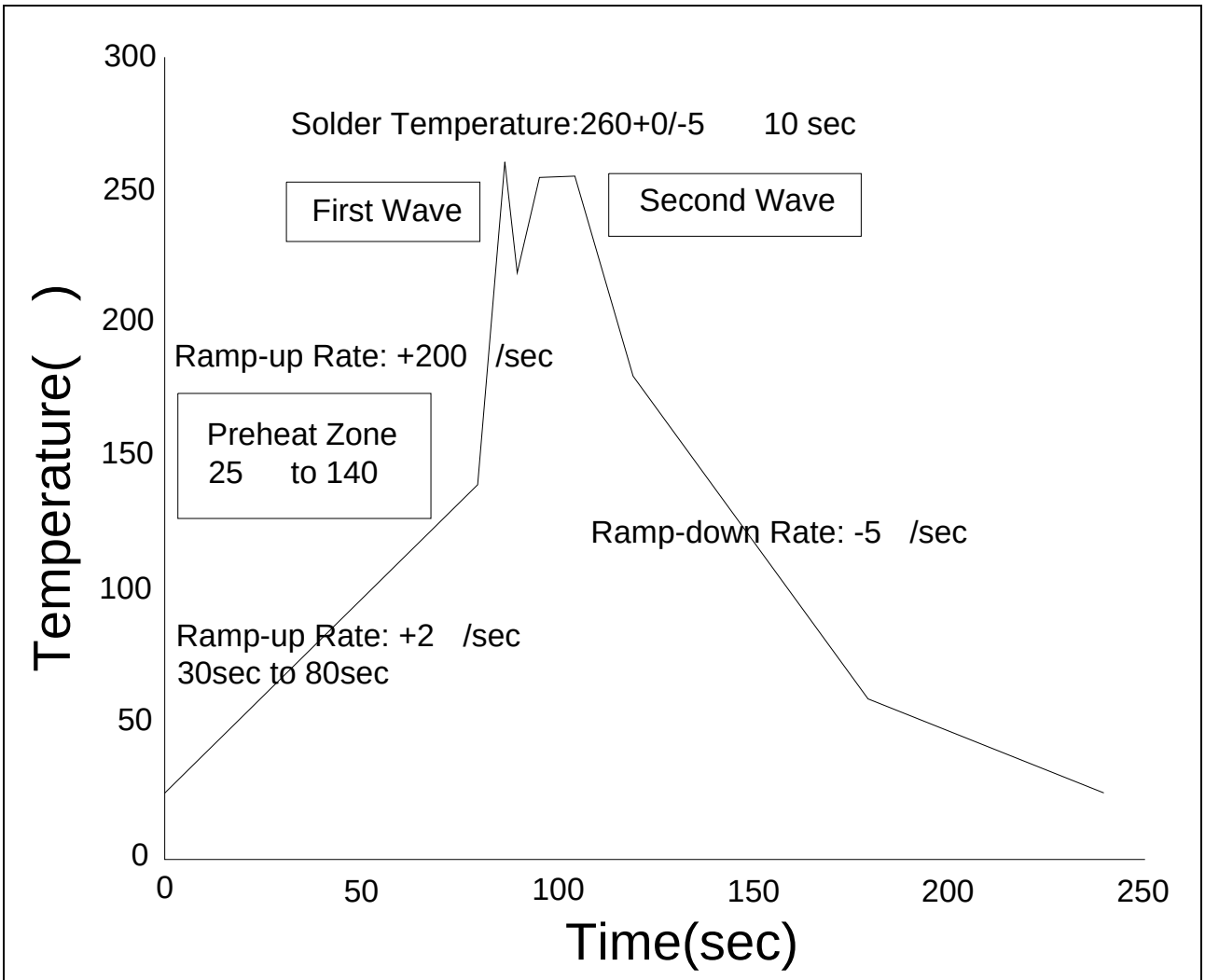


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

Option L

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50			0.059	
P0	3.90	4.00		0.154	0.157	
P1	11.90	12.00		0.469	0.472	
P2	1.90	2.00		0.075	0.079	
E	1.65	1.75		0.065	0.069	
F	7.40	7.50		0.291	0.295	
T	0.35	0.40		0.014	0.016	
W	15.70	16.00	16.30	0.618	0.630	0.642

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

Information furnished in this document is believed to be accurate and reliable. However,
Jiangsu JieJie Microelectronics Co., Ltd. sjelekdlovJiang-e éent nonros, ndenonC;d fr wheJiose quac